YCP

- ■ <Popular edition> solder-paste printer packaged with standard functions and specifications.
- ■ High-speed printing tact 15.2 sec (Under optimum conditions)
- ■ Positioning repeatability is +/-15μm
- ■ Sturdy frame and highly rigid printing table assure high printing quality and stability.

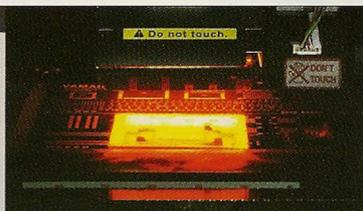Note : The photo shows the state with various options installed.

Cleaning system

The cleaning system assures high quality of difficult printing such as very small chips & fine pitch QFP patterns.
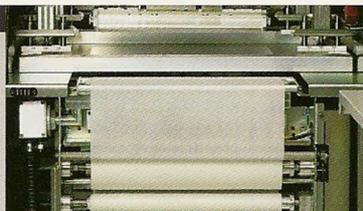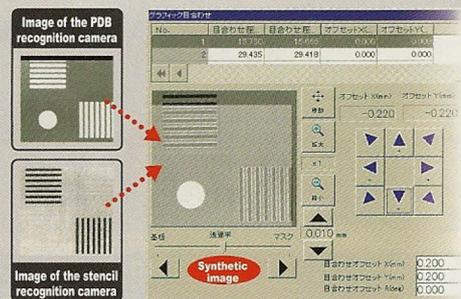
Print inspection camera

High-speed capture is executed by the digital camera with high resolution and wide field-of-view.

Graphical layer base alignment function

Even when the stencil opening shape and the PCB pattern shape are different, images from two cameras are combined in layer, thereby operation of the PCB to printing stencil relative positioning can be performed simply and accurately.

Image of the PDB recognition camera

Image of the stencil recognition camera

Synthetic image

■ YCP specifications (Model : KHU-000)

	YCP		
Applicable PCB	L330 x W250mm to L50 x W50mm		
Printing heads	Double squeegee head (Either metal squeegee or urethane squeegee to be selected)		
	Printing speed : 2 to 200mm/sec		
Printing accuracy	positioning repeatability (3σ) : +/-0.015mm		
Printing line tact	15.2 sec (Normal printing : L180 x W130mm Under optimum conditions)		
	12.4 sec (Operation time other than printing : Loading PCB + Fixing PCB		
Applicable stencil size	L650 x W550mm	L600 x W550mm	L550 x W650mm
<Note 1>	○	○	○
Power supply	Single-phase AC 200 to 230V +/-10% 50/60Hz		
Air supply source	0.55MPa or more, in clean, dry state		
External dimension <Note 2>	L1,315 x W1,580 x H1,310mm (cover top)		
Weight	Approx.1,200kg		

<Note 1> Applicable= ○
<Note 2> This dimension does not include the projection.